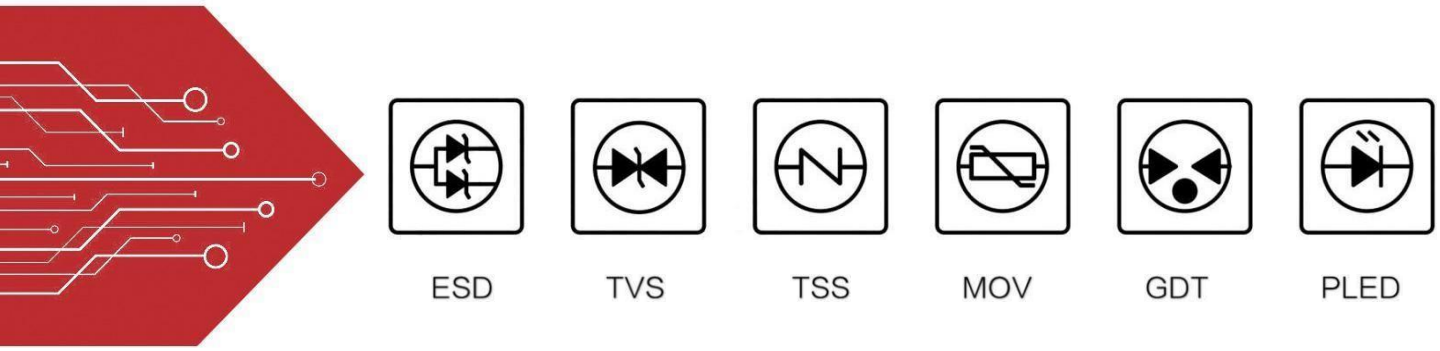
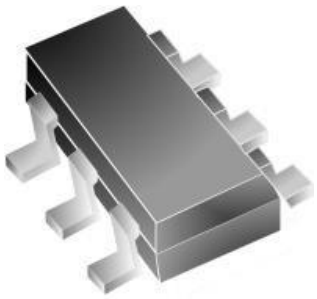
MSKSEMI
SEMICONDUCTOR



Product data sheet

Features

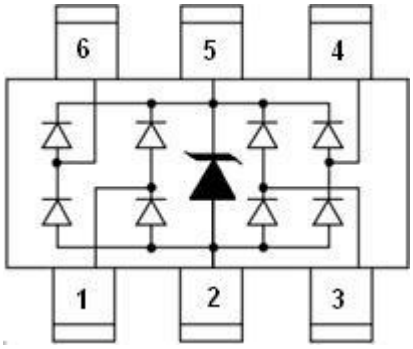
- 150 watts peak pulse power per line(t_P=8/20μs)
- Protects four I/O lines
- Low clamping voltage
- Low operating voltage
- Low capacitance
- RoHS compliant



SOT-23-6

MAIN APPLICATIONS

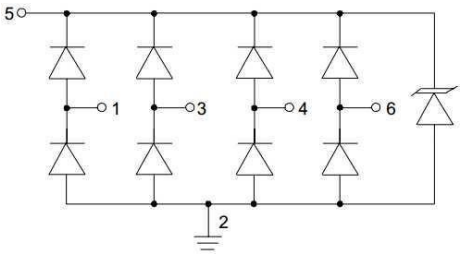
- USB 2.0&3.0 power and data line protection
- Digital video interface (DVI)
- Notebook computers
- Video graphics cards
- Monitors and flat panel displays
- 10/100/1000 ethernet
- SIM ports
- ATM interfaces



PIN Configuration

PROTECTION SOLUTION TO MEET

- IEC61000-4-2 (ESD) ±20kV (air), ±20kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 5A (8/20μs)



Circuit Diagram

MECHANICAL CHARACTERISTICS

- Molding compound flammability rating: UL 94V-0
- Quantity per reel: 3, 000pcs
- Lead finish: lead free

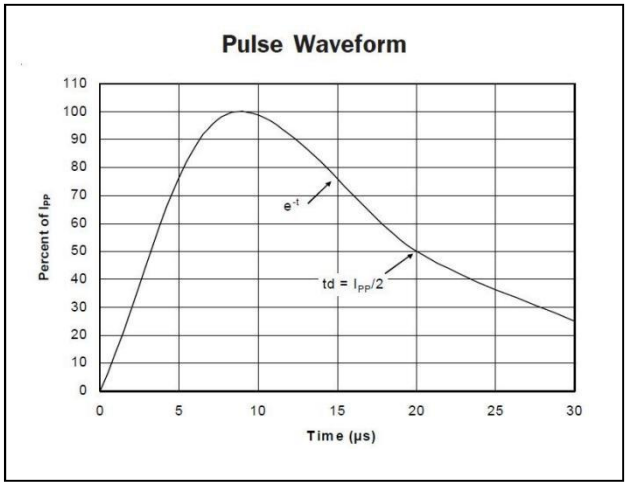
ABSOLUTE MAXIMUM RATINGS (T_A=25℃, RH=45%-75%, unless otherwise noted)

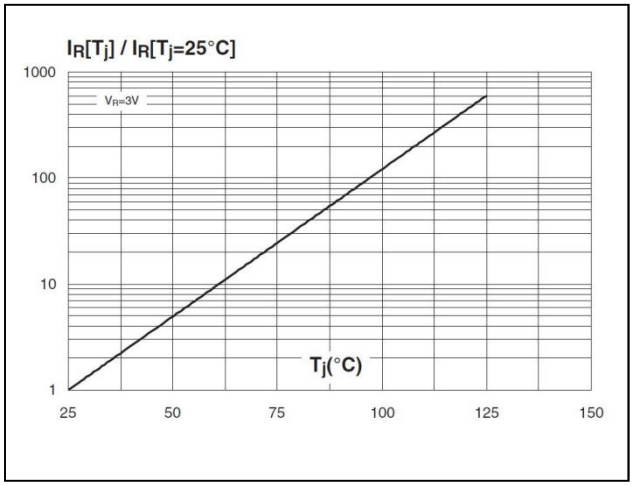
Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P_{PP}	150	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 20 +/-20	kV
Lead soldering temperature	T_L	260 (10 sec.)	℃
Operating junction temperature range	T_J	-55 to +125	℃
Storage temperature range	T_{STG}	-55 to +150	℃

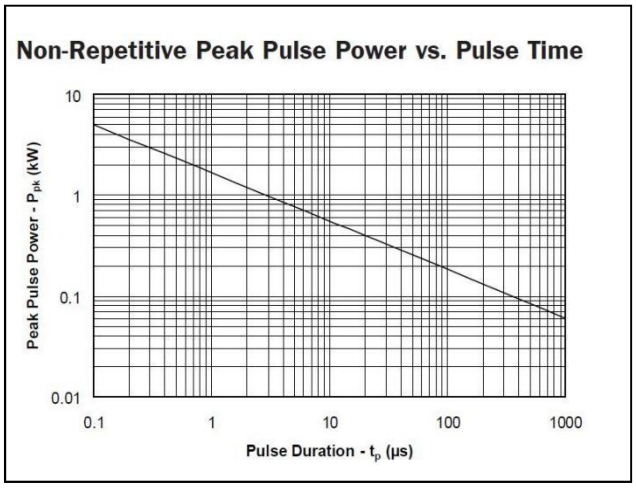
ELECTRICAL CHARACTERISTICS (T_A=25℃)

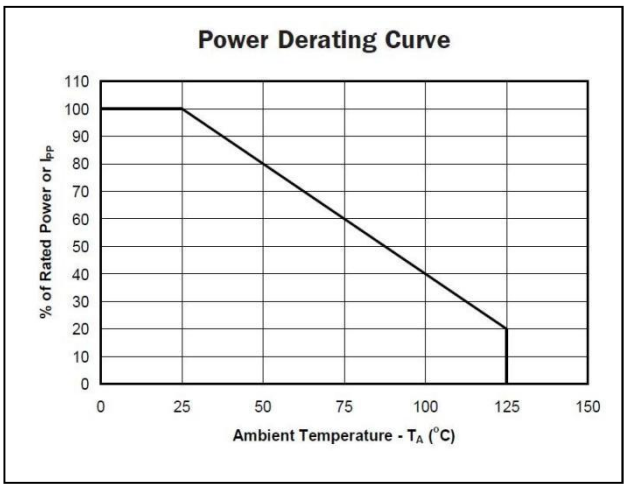
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				5.0	V
Reverse breakdown voltage	V_{BR}	I_T=1mA	6.0			V
Reverse leakage current	I_R	V_{RWM}=5V			1	μA
Forward voltage	V_F	I_T=10mA		0.8	1.0	V
Clamping voltage (I/O pin to Ground)	V_C	I_{PP}=1A, t_P=8/20μs		9.5	11	V
	V_C	I_{PP}=5A, t_P=8/20μs		12.5	15	
Junction capacitance	C_J	V_{RWM}=0V, f=1MHz Any I/O pin to Ground		0.65	0.8	pF
		V_{RWM}=0V, f=1MHz Between I/O pins		0.3	0.5	

Typical Characteristics@ Ta=25℃ unless otherwise specified



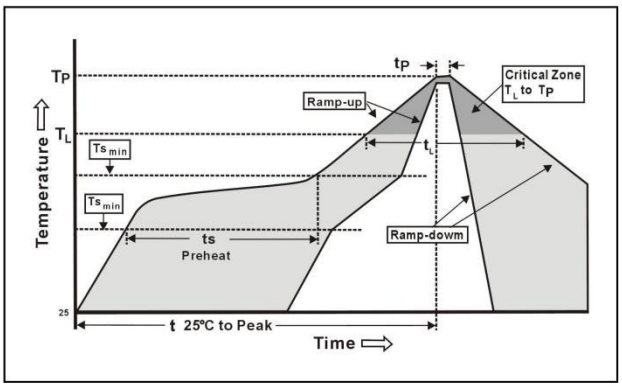




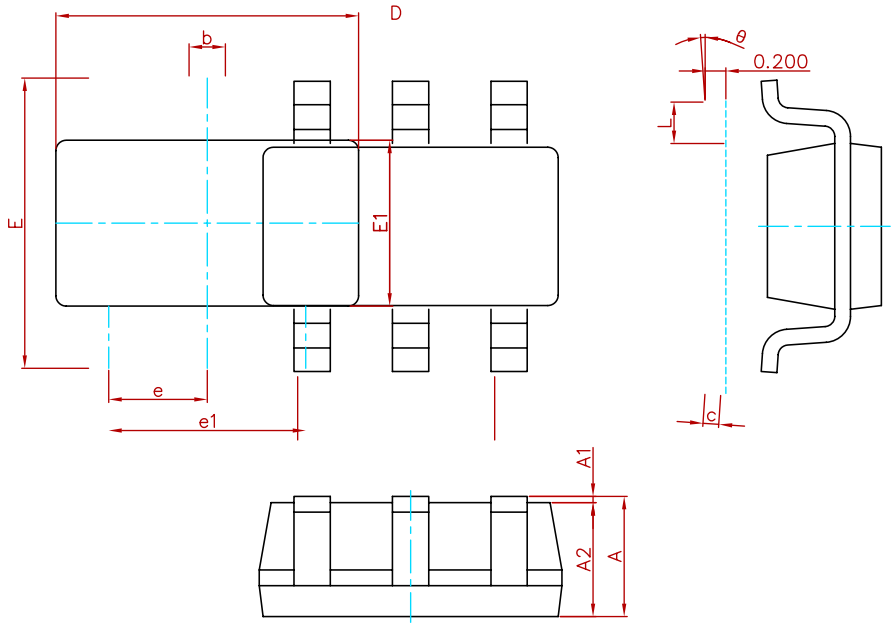


Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	-Temperature Min ($T_{s(Min)}$)	150°C
	-Temperature Max ($T_{s(Max)}$)	200°C
	-Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{S(Max)}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		$250^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-dowm Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

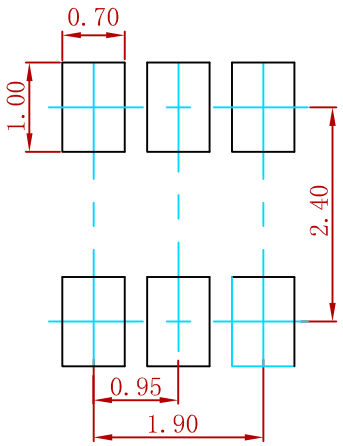


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PDWL050019-MS	SOT-23-6	3000

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